TIDA-00891 USB TypeC™ Receptacle to USB Type-A Receptacle SS MUX with UFP Controller Reference Design

REVA

USB Type A Receptacle

Type C Connector

HD3SS3220

TUSB211

VBUS

CC1/CC2

SS TX2_RX2

SS TX1_RX1

DP

DM

SS TX_RX

VBUS
1. Install only if active discharge circuit exists.
2. CUR_MD valid only in DFP mode.
3. Bulk cap for VCONN between 10uF to 220uF
4. C18, C20, R39, R40, R41 and R42 are placed for interoperability purposes with USB Vcm above 2V.
5. C17, C19, C21 and C22 are placed for interoperability purposes with USB Vcm above 2V.
6. ALL DIFF PAIRS ARE ROUTED 85 TO 90 OHMS DIFFERENTIAL AND 50 OHMS COMMON MODE. ALL OTHER TRACES ARE 50 OHMS.
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